



P-Channel 30-V (D-S) MOSFET

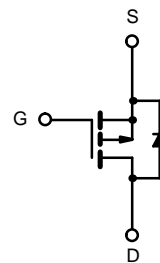
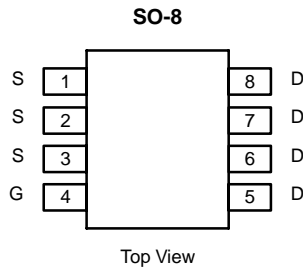
PRODUCT SUMMARY		
V_{DS} (V)	$r_{DS(on)}$ (Ω)	I_D (A)
-30	0.018 @ $V_{GS} = -10$ V	-9.6
	0.030 @ $V_{GS} = -4.5$ V	-7.5

FEATURES

- TrenchFET® Power MOSFET
- Advanced High Cell Density Process

APPLICATIONS

- Load Switches
 - Notebook PCs
 - Desktop PCs



Ordering Information: Si4835BDY
Si4835BDY-T1 (with Tape and Reel)

ABSOLUTE MAXIMUM RATINGS ($T_A = 25^\circ\text{C}$ UNLESS OTHERWISE NOTED)					
Parameter	Symbol	10 secs	Steady State	Unit	
Drain-Source Voltage	V_{DS}	-30		V	
Gate-Source Voltage	V_{GS}	± 25			
Continuous Drain Current ($T_J = 150^\circ\text{C}$) ^a	I_D	$T_A = 25^\circ\text{C}$	-9.6	-7.4	A
		$T_A = 70^\circ\text{C}$	-7.7	-5.9	
Pulsed Drain Current	I_{DM}	-50			
continuous Source Current (Diode Conduction) ^a	I_S	-2.1	-1.3		
Maximum Power Dissipation ^a	P_D	$T_A = 25^\circ\text{C}$	2.5	1.5	W
		$T_A = 70^\circ\text{C}$	1.6	0.9	
Operating Junction and Storage Temperature Range	T_J, T_{stg}	-55 to 150		$^\circ\text{C}$	

THERMAL RESISTANCE RATINGS					
Parameter	Symbol	Typical	Maximum	Unit	
Maximum Junction-to-Ambient ^a	R_{thJA}	$t \leq 10$ sec	39	50	$^\circ\text{C/W}$
		Steady State	70	85	
Maximum Junction-to-Foot (Drain)	R_{thJF}	18	22		

Notes

a. Surface Mounted on 1" x 1" FR4 Board.

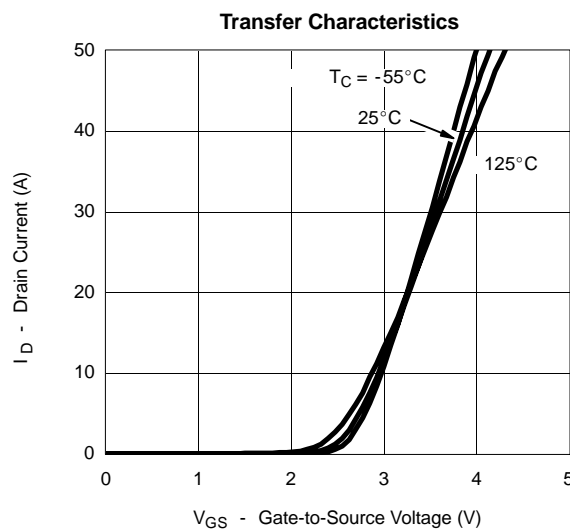
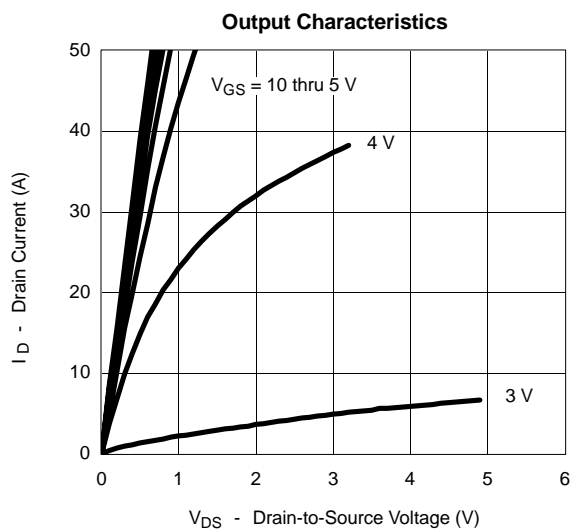
SPECIFICATIONS (T_J = 25 °C UNLESS OTHERWISE NOTED)

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Static						
Gate Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = -250 μA	-1.0		-3.0	V
Gate-Body Leakage	I _{GSS}	V _{DS} = 0 V, V _{GS} = ±25 V			±100	nA
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = -24 V, V _{GS} = 0 V			-1	μA
		V _{DS} = -24 V, V _{GS} = 0 V, T _J = 55 °C			-5	
On-State Drain Current ^a	I _{D(on)}	V _{DS} ≤ -5 V, V _{GS} = -10 V	-50			A
Drain-Source On-State Resistance ^a	r _{DS(on)}	V _{GS} = -10 V, I _D = -9.6 A		0.014	0.018	Ω
		V _{GS} = -4.5 V, I _D = -7.5 A		0.023	0.030	
Forward Transconductance ^a	g _{fs}	V _{DS} = -15 V, I _D = -9.6 A		30		S
Diode Forward Voltage ^a	V _{SD}	I _S = -2.1 A, V _{GS} = 0 V		-0.8	-1.2	V
Dynamic^b						
Total Gate Charge	Q _g	V _{DS} = -15 V, V _{GS} = -5 V, I _D = -9.6 A		25	37	nC
Gate-Source Charge	Q _{gs}			6.5		
Gate-Drain Charge	Q _{gd}			12.5		
Gate Resistance	R _g		1.0	2.9	4.9	Ω
Turn-On Delay Time	t _{d(on)}	V _{DD} = -15 V, R _L = 15 Ω I _D ≅ -1 A, V _{GEN} = -10 V, R _G = 6 Ω		15	25	ns
Rise Time	t _r			13	20	
Turn-Off Delay Time	t _{d(off)}			60	100	
Fall Time	t _f			45	70	
Source-Drain Reverse Recovery Time	t _{rr}		I _F = -2.1 A, di/dt = 100 A/μs		45	

Notes

- a. Pulse test; pulse width ≤ 300 μs, duty cycle ≤ 2%.
- b. Guaranteed by design, not subject to production testing.

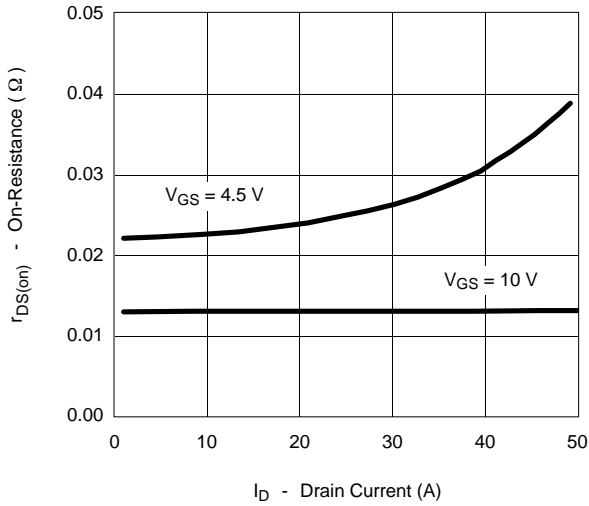
TYPICAL CHARACTERISTICS (25 °C UNLESS NOTED)



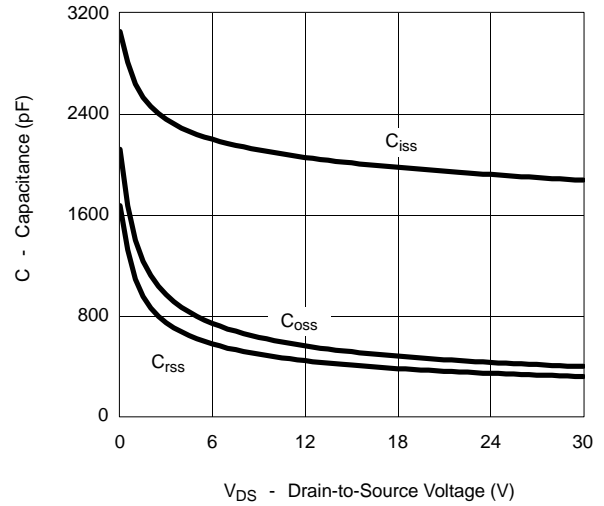


TYPICAL CHARACTERISTICS (25 °C UNLESS NOTED)

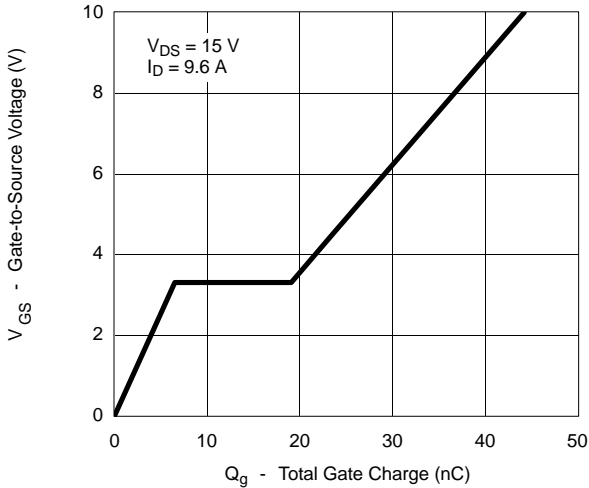
On-Resistance vs. Drain Current



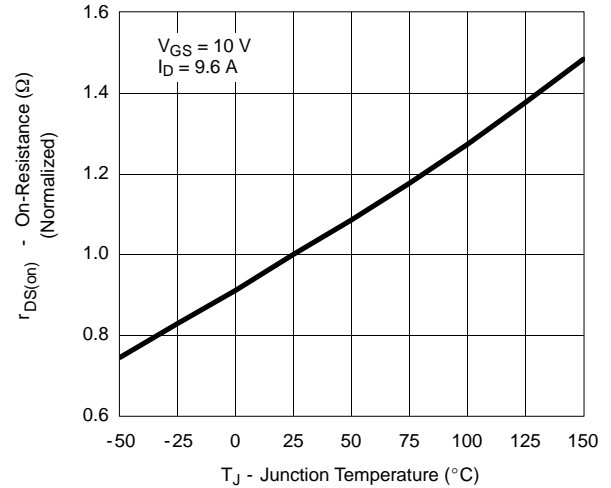
Capacitance



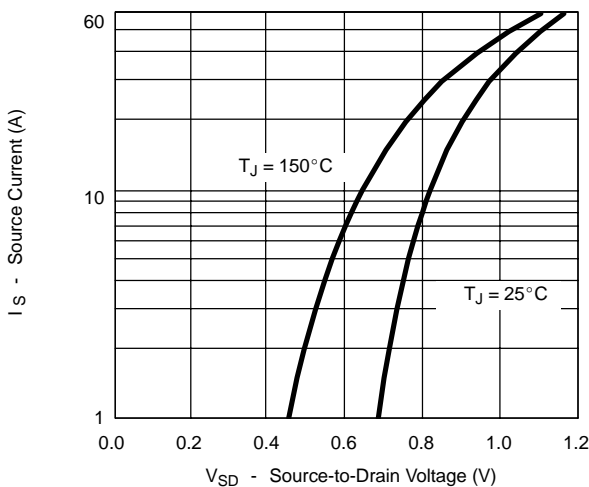
Gate Charge



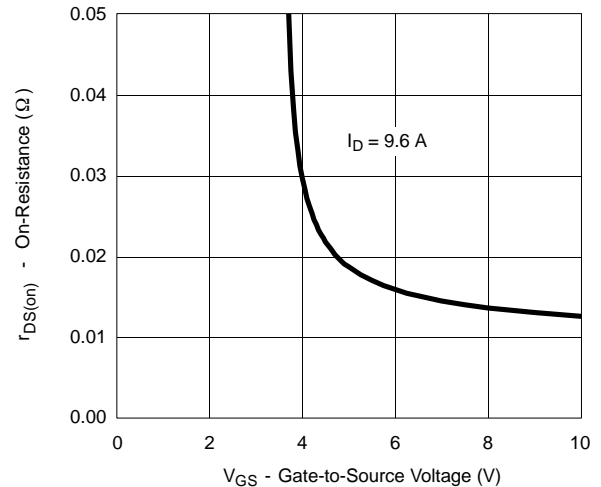
On-Resistance vs. Junction Temperature



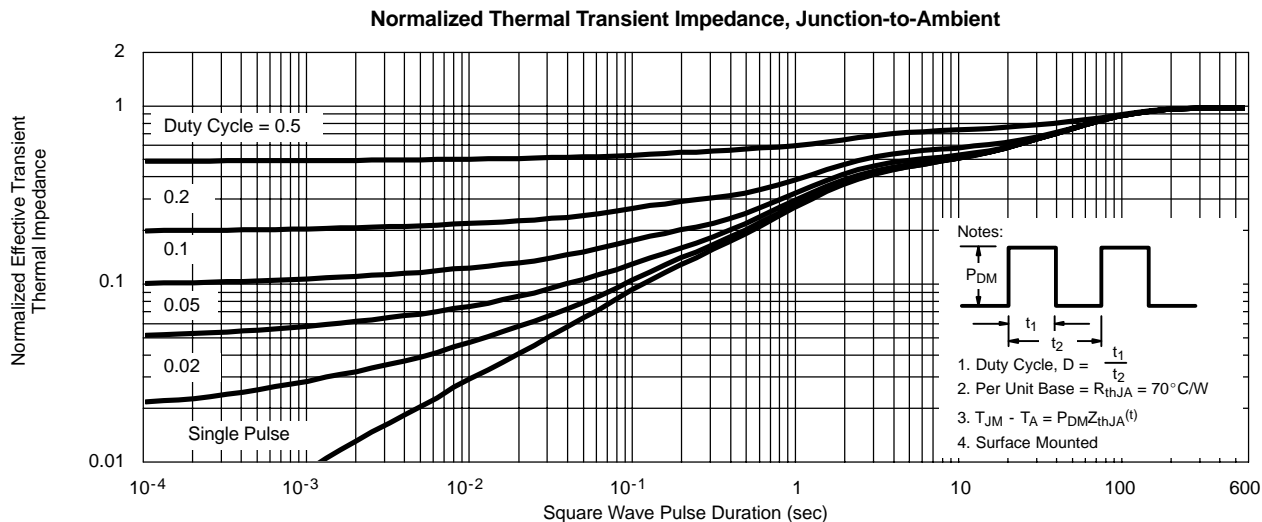
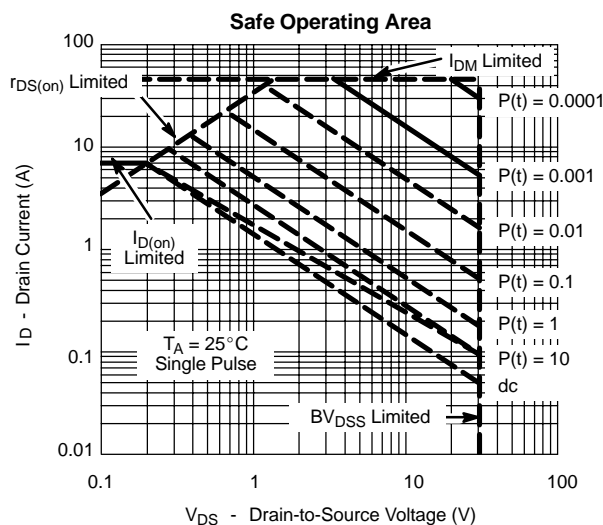
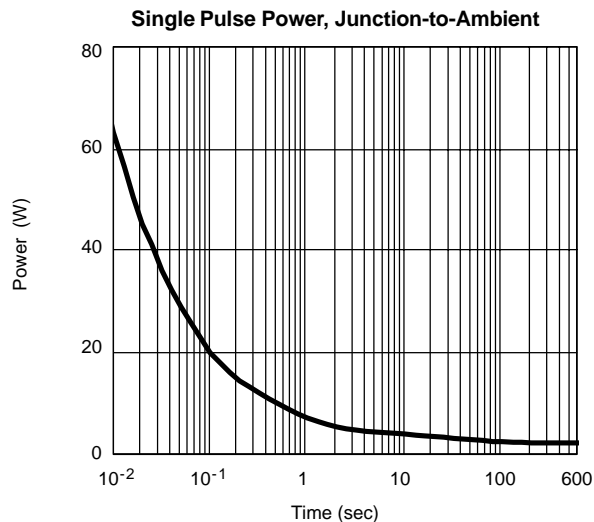
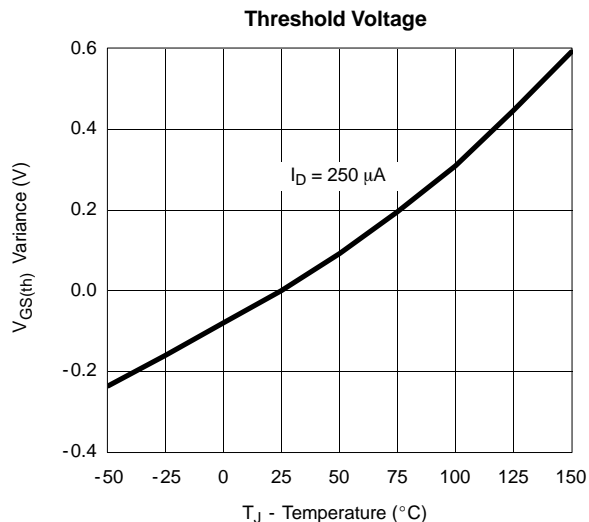
Source-Drain Diode Forward Voltage



On-Resistance vs. Gate-to-Source Voltage



TYPICAL CHARACTERISTICS (25 °C UNLESS NOTED)





TYPICAL CHARACTERISTICS (25°C UNLESS NOTED)

Normalized Thermal Transient Impedance, Junction-to-Foot

